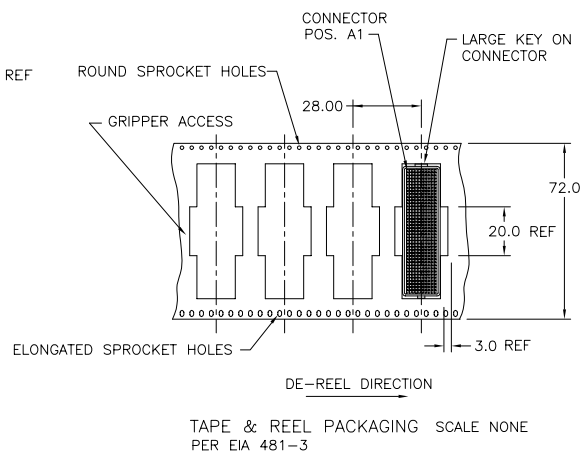
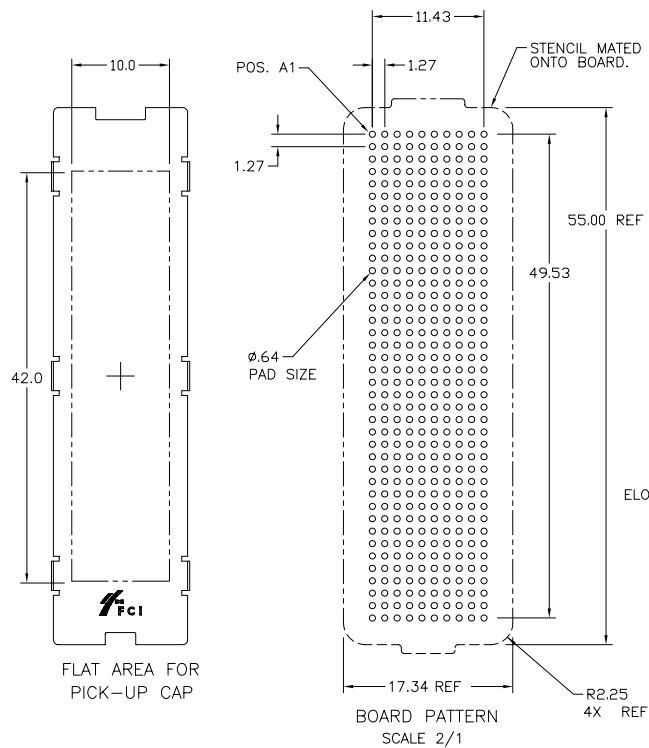


mat'l. code	SEE NOTE 1	surface	tolerance	projection	product family
ASME Y14.5	ASME Y14.5	ASME Y14.5	ASME Y14.5	ASME Y14.5	MEG-ARRAY
tolerances unless otherwise specified	tolerances unless otherwise specified	tolerances unless otherwise specified	tolerances unless otherwise specified	tolerances unless otherwise specified	tolerances unless otherwise specified
angles	angles	angles	angles	angles	angles
mm	mm	mm	mm	mm	mm
scale 3:1	scale 3:1	scale 3:1	scale 3:1	scale 3:1	scale 3:1
dwg no	dwg no	dwg no	dwg no	dwg no	dwg no
74221	74221	74221	74221	74221	74221
type	type	type	type	type	type
CUSTOMER Drawing	CUSTOMER Drawing	CUSTOMER Drawing	CUSTOMER Drawing	CUSTOMER Drawing	CUSTOMER Drawing



mat'l. code	SEE NOTE 1	surface	ASME Y14.5	tolerance	ASME Y14.5	projection	product family
thr	ecn no	dr	date	tolerances unless otherwise specified			MEG-ARRAY
N				angles	X*3	MM	title
				0° ±2°	XXX*9	scale 2:1	4mm RECPT. ASSY
					XXXX*051		10x40= 400 POS.
		dr	D WAUGHEN	11.26.97			dwg no
		engr	T LEMKE	11.26.97			74221
		chr	T LEMKE	11.26.97			sheet 2 of 3
		appd	T LEMKE	11.26.97			size
sheet index	revision sheet						A4
							type
							CUSTOMER Drawing

PRODUCT NUMBER	PICK-UP CAP	CONTACT PLATING	SOLDER BALL
74221-001	YES	15u" (.38um) Au OVER Ni	SnPb
74221-001LF			SnAgCu LEAD FREE (6)(7)
74221-101	YES	30 u" (.76um) Au OVER Ni	SnPb
74221-101LF			SnAgCu LEAD FREE (6)(7)
74221-201	YES	SEE NOTE 5.	SnPb
74221-201LF			SnAgCu LEAD FREE (6)(7)

NOTES:

①. MAT'L:

HOUSING: LCP

CONTACT: COPPER ALLOY

PLATING

CONTACT: (SEE TABLE ON SHEET3)
 SOLDER BALL: (SEE TABLE ON SHEET3)
 EUTECTIC SnPb OR LEAD FREE
 95.5Sn/4Ag/0.5Cu

②. SOLDER BALLS WILL NOT BE PERFECT SPHERICAL SHAPE
 DUE TO REFLOW ATTACHMENT.

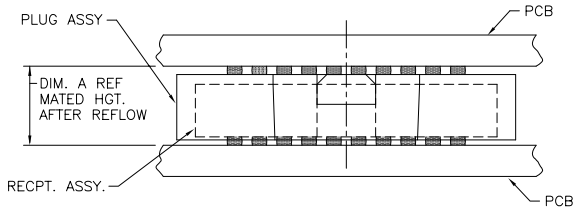
③. MATED HEIGHT EFFECTED BY CUSTOMER'S PCB PAD SIZE,
 PLATING, SOLDER REFLOW PROFILE, & SOLDER PASTE.

④. NO TIN/LEAD OR FLUX ABOVE TERMINAL SHOULDER.

⑤. PLATING FOR -2XX SERIES DASH NOS. MEETS
 THE REQUIREMENTS OF NORTEL NPS25298-2
 (CENTRAL OFFICE ENVIRONMENT, 25 YEAR LIFE EXPECTANCY).

⑥. FOR PROPER APPLICATION FOLLOW FCI APPLICATION
 SPECIFICATION GS-20-033 LEAD FREE SOLDER BALLS WILL
 NOT SOLDER PROPERLY IN A LEADED SOLDER PROCESS
 DUE TO A HIGHER REFLOW TEMPERATURE. LEAD FREE
 PRODUCT IS THEREFORE NOT BACKWARDS COMPATIBLE WITH
 LEADED OR SOME SOLDERING APPLICATIONS. REFERENCE
 FCI APPLICATION SPECIFICATION

⑦. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND
 OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008
 PRODUCT MEETING THIS DIRECTIVE IS IDENTIFIED IN THE LOT
 CODE NUMBER MARKED ON EACH PART BY HAVING AN "X"
 IN THE SEVENTH CHARACTER POSITION



MATED HEIGHT TABLE		
DIM. A	PLUG ASSY P/N	RECPT. ASSY P/N
4.0	84740	74221
10.0	84520	74221

MATED HEIGHT AFTER REFLOW IS BASED ON Ø .64mm PAD (METAL-DEFINED)
 AND .13mm SOLDER PASTE STENCIL THICKNESS. SEE NOTE 3.

END VIEW — MATED CONNECTORS SCALE NONE

mat'l. code	SEE NOTE 1	surface	ASME Y14.5	tolerance	ASME Y14.5	projection	product family
lit	ecm no	dir	date	tolerances unless otherwise specified			MEG-ARRAY
N				angles	X*3	MM	title
					XXX*3		4mm RECPT. ASSY
				0° ±2°	XXXX*051	scale 2:1	10x40= 400 POS.
				dr	D WAUGHEN 11.26.97		dwg no
				enqr	T LEMKE 11.26.97		74221
				chr	T LEMKE 11.26.97		sheet 3 of 3
				appd	T LEMKE 11.26.97		size A4
sheet index	revision sheet						type CUSTOMER Drawing